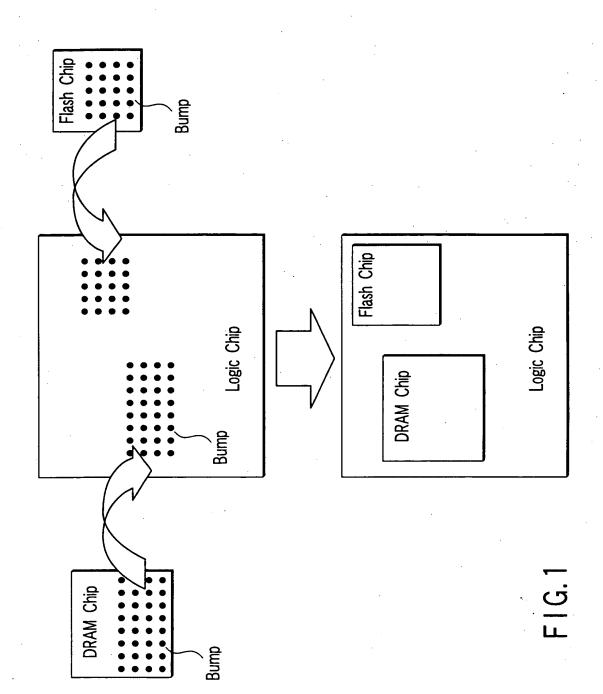
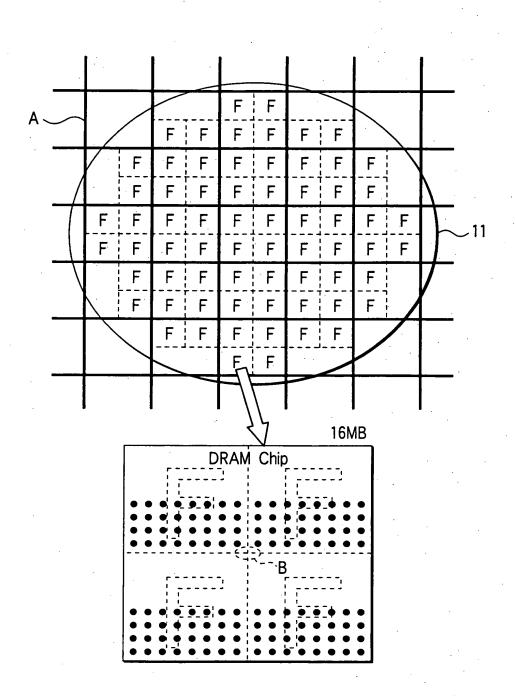
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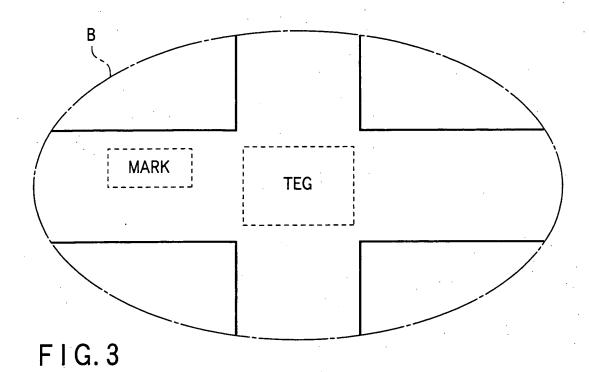


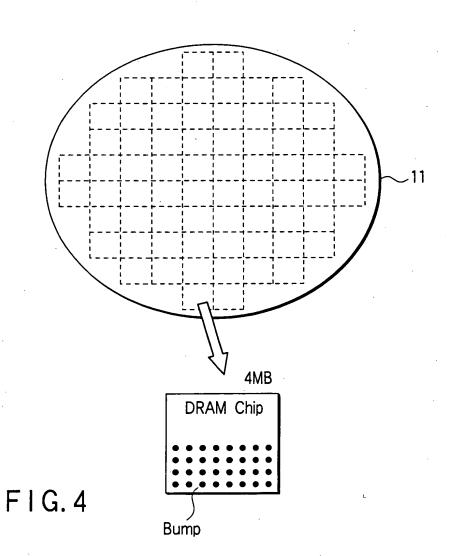
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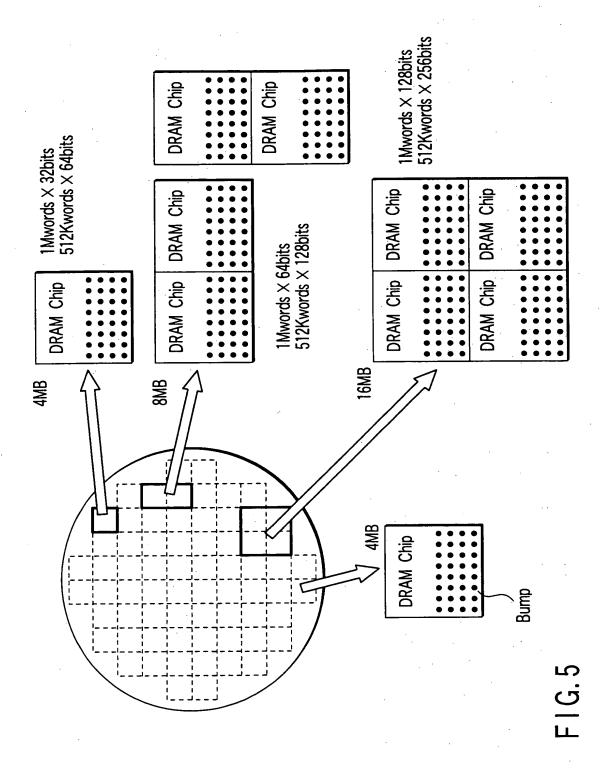
F I G. 2

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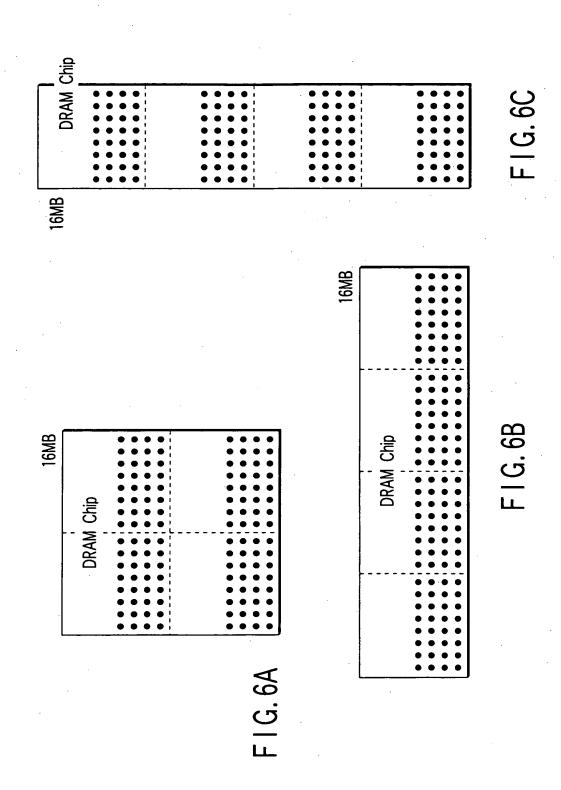




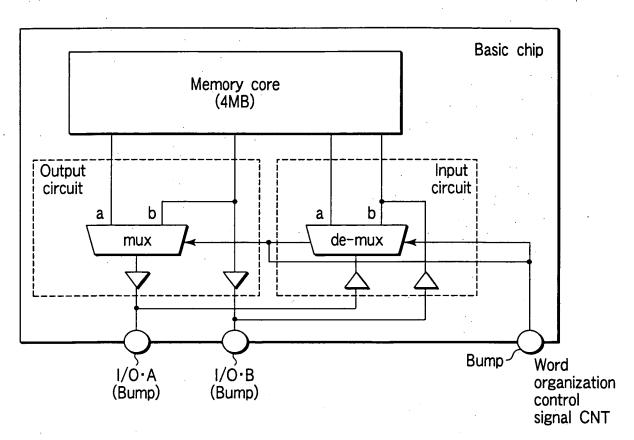
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F I G. 7

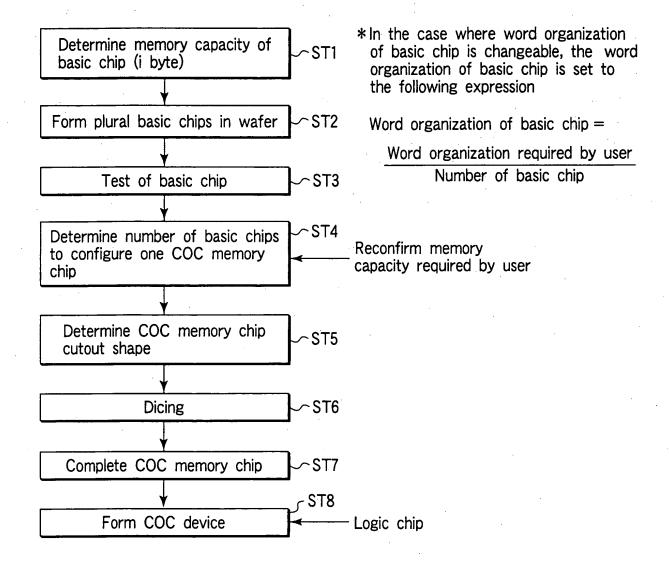
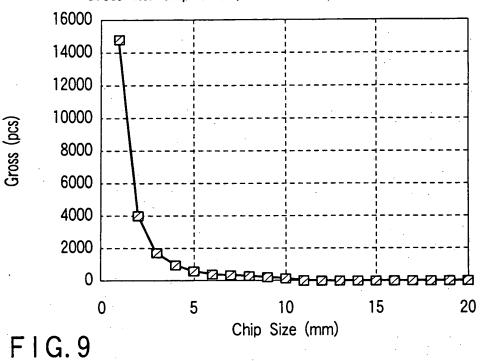


FIG. 8

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Gross v.s. Chip Size (6-inch wafer)



Chip Efficiency v.s. Chip Size (6-inch wafer)

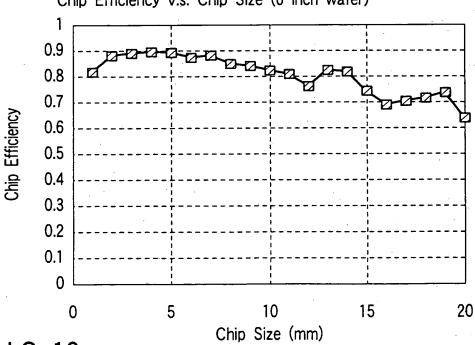
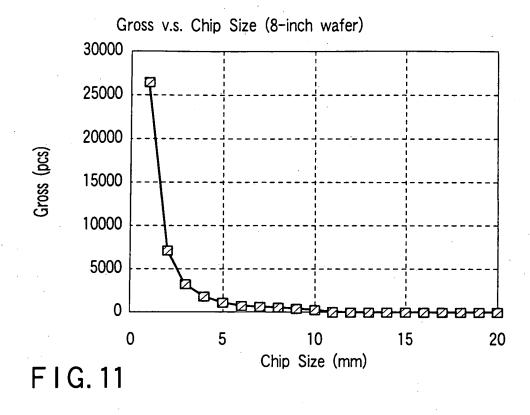
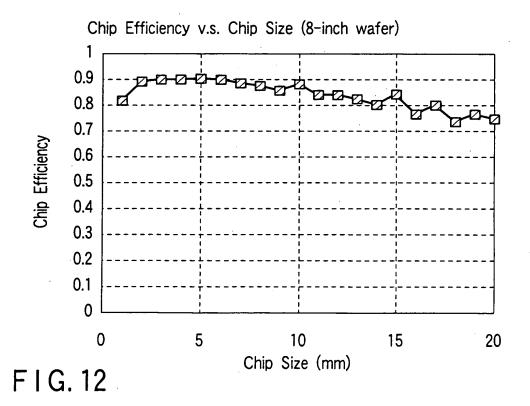


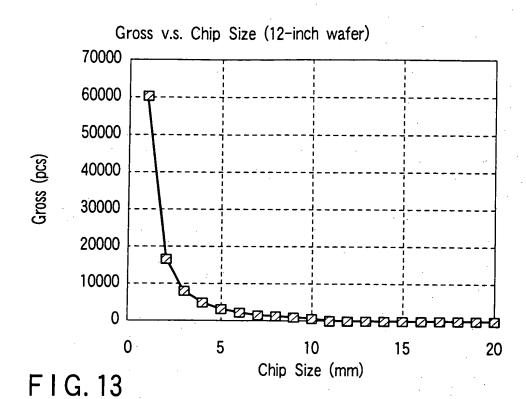
FIG. 10

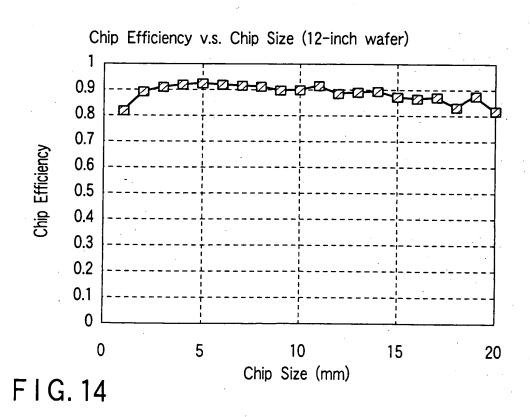
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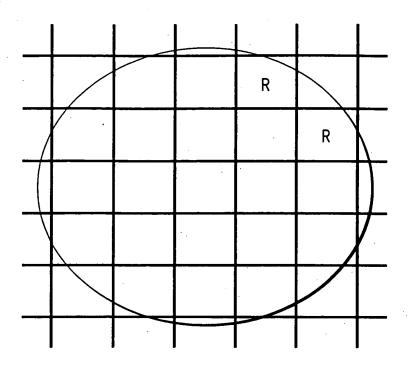
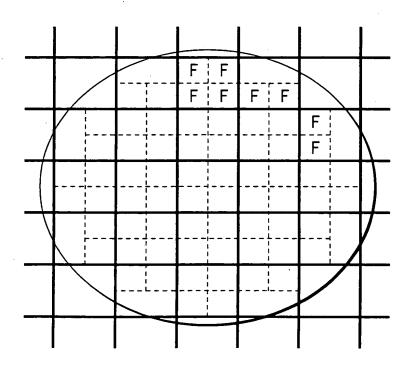
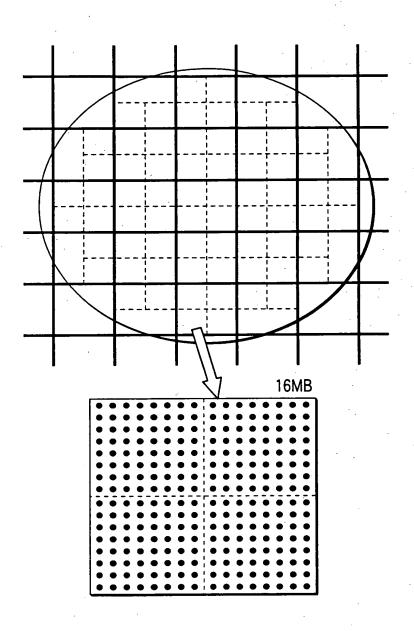


FIG. 15A PRIOR ART



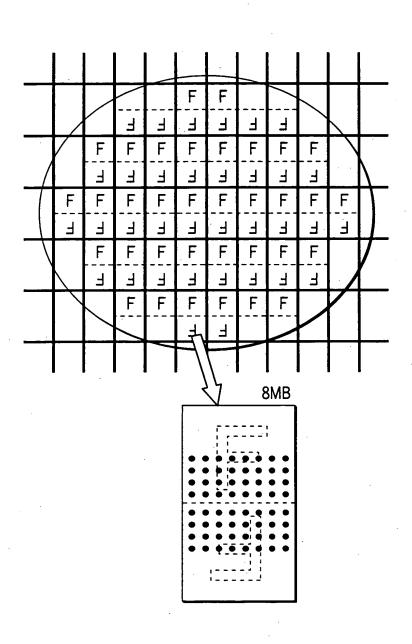
F I G. 15B

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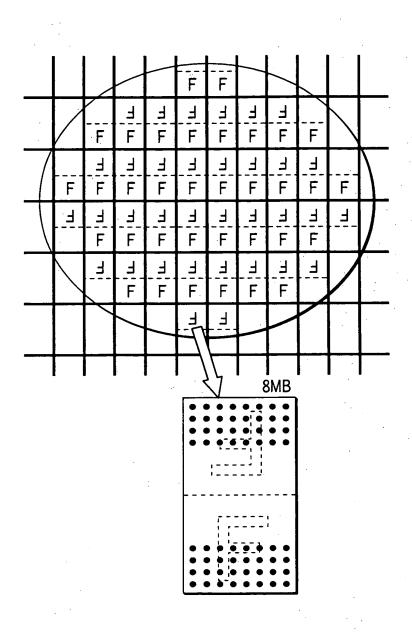
F I G. 16

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F I G. 17

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F I G. 18

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MCM 1

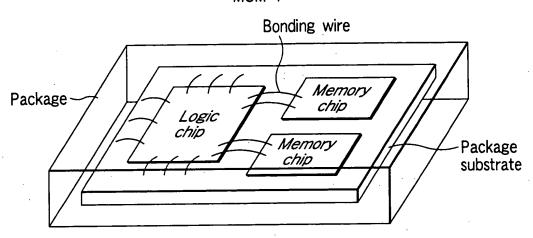
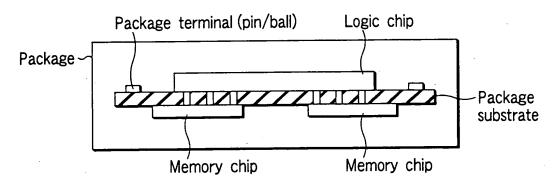


FIG. 19

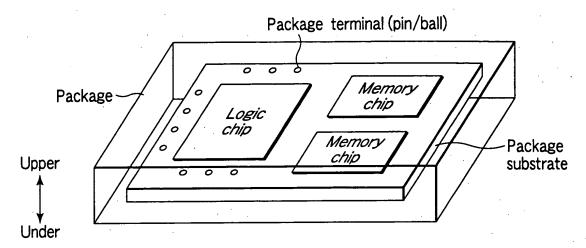
MCM 3



F I G. 21

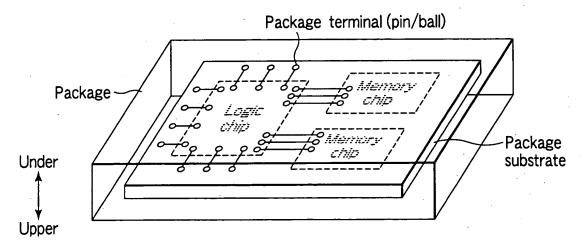
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MCM 2



F I G. 20A

MCM 2



F I G. 20B